ITEQ Corporation

2021 Third Quarter Earnings Result

ITEQ

INNOVATION. TEAMWORK. EXCELLENCE. QUALITY

Disclaimer Statement



- This presentation and release contain "forward-looking statements" which may include projections
 of future results of operations, financial condition or business prospects based on our own
 information and other sources.
- Our actual results of operations, financial condition or business prospects may differ from those expressed or implied in these forward-looking statements for a variety of reasons, including but not limited to market demand, price fluctuations, competition, international economic conditions, supply chain issues, exchange rate fluctuations and other risks and factors beyond our control.
- The forward-looking statements in this release reflect the current belief of ITEQ as of the date of this release. ITEQ undertakes no obligation to update these forward-looking statements for events or circumstances that occur subsequent to such date.

Company Overview

◆ Establishment: April 10th, 1997

◆ Headquarters: HsinChu, Taiwan

◆ Capital: NTD\$3,830M

◆ Employees: Over 3,000

Chairman: Dennis Chen

◆ CEO: Audrey Tsai

◆ Main Product: Copper Clad Laminate & Prepreg

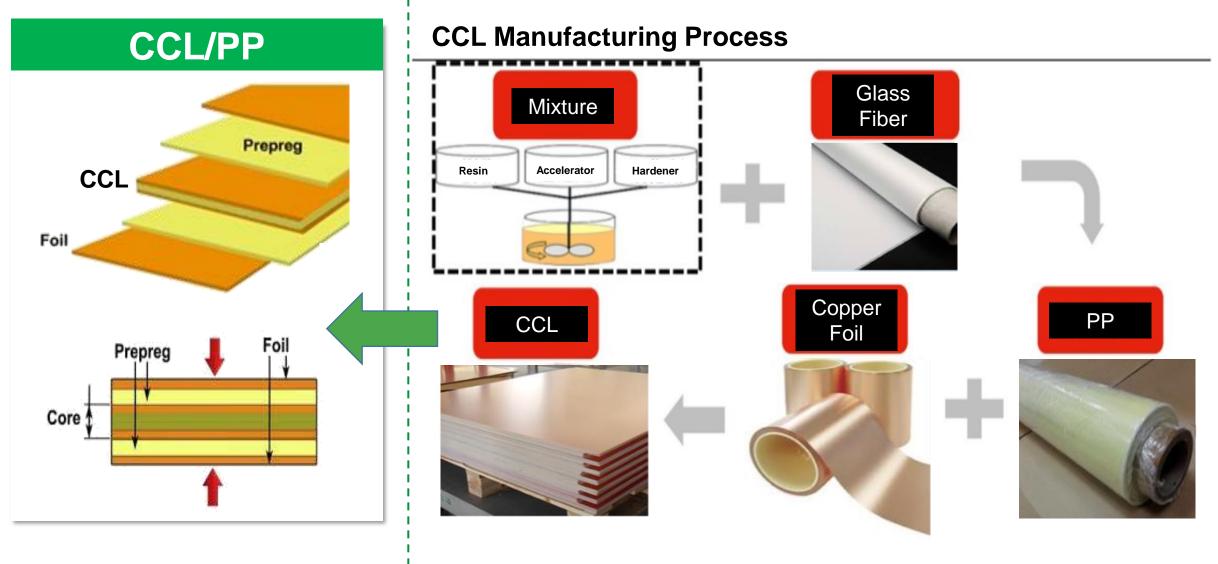
Flexible CCL

Masslam service



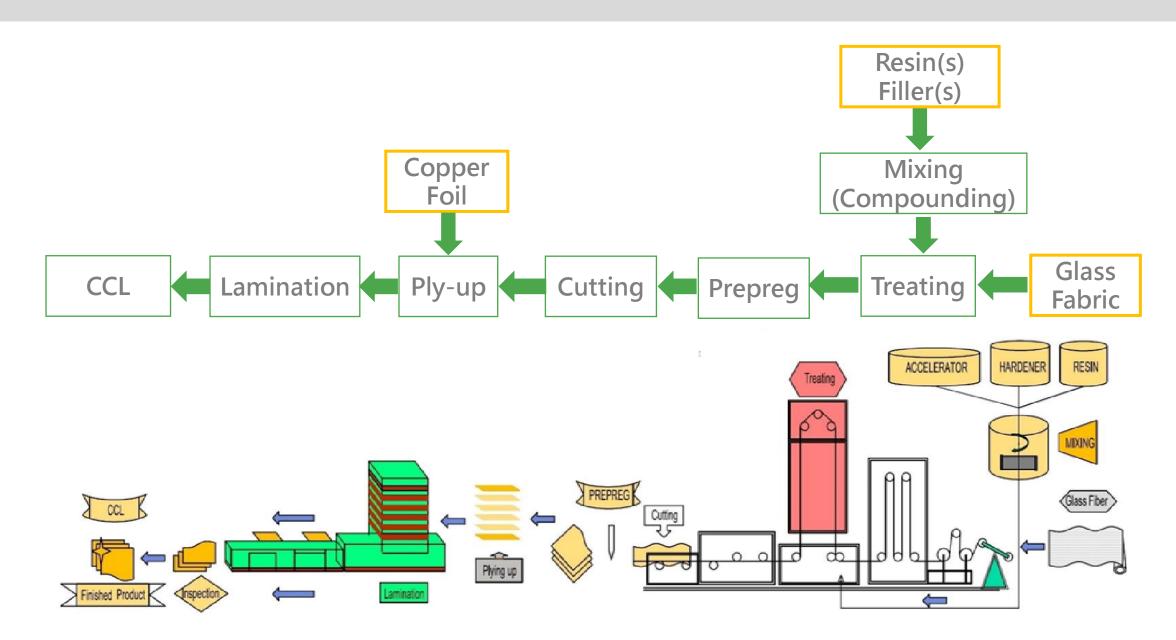
CCL & PP Composite Structure





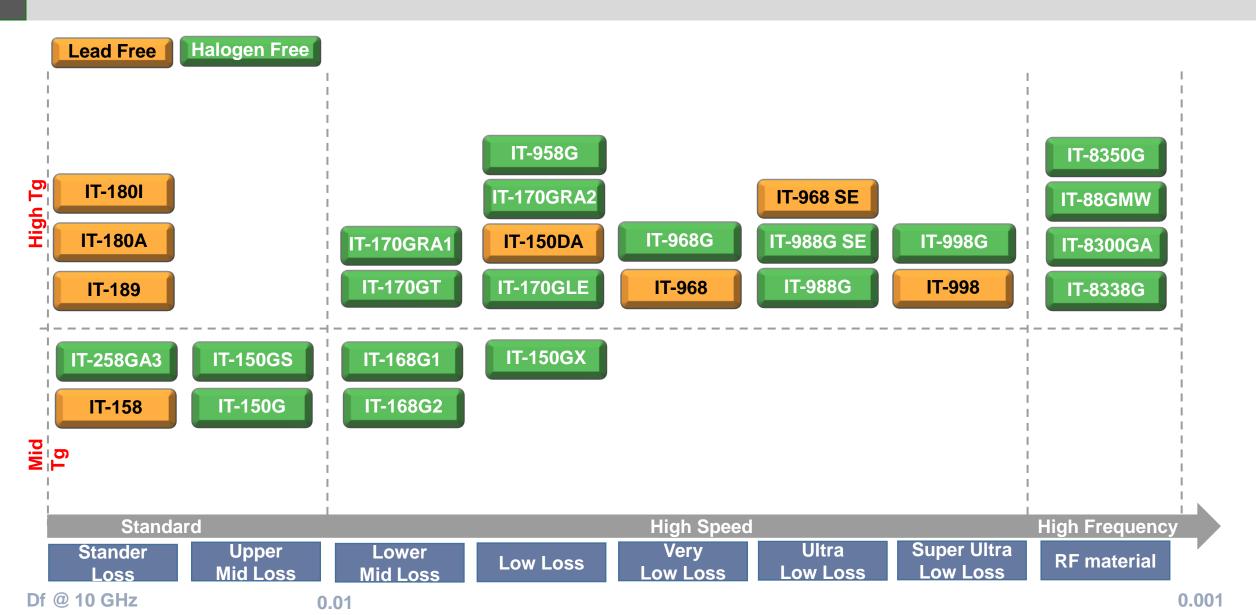
CCL & PP Manufacturing Flow





Product Roadmap





Core Technology





Smartphone

Tablet

Low Dk Ultrathin



Networking
Datacenter
Cloud Computing
5G

Controlled Dk and Low Df

Material
Science
Resin
Mixture
Process
Engineering

FR-4 Halogen Free

Consumer Electronics





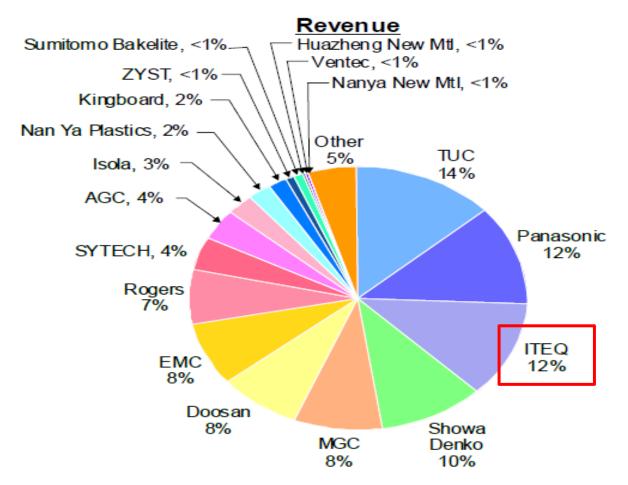
Automotive Electronics



Market Share Leader in Specialty Laminate



2020 WW Specialty Laminate Market Share



TOTAL: \$3.93Bn (\$USD)

- Worldwide top supplier in high speed / frequency laminate
- Cutting-edge technology with MP track record
- Secular growth momentum in 5G network and data center opportunities
- Rising EV market to boost demand for high speed / frequency automotive CCL



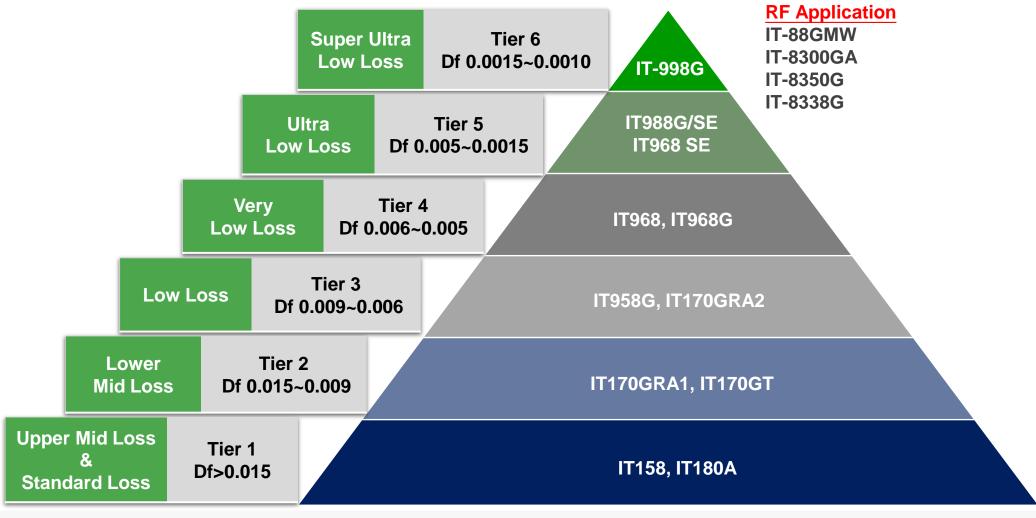
Source: Prismark Report, 2021/06

ITEQ: Leading CCL supplier

^{*}Specialty Laminate includes: High speed, package substrate, RF

Well-Expanded Product Line

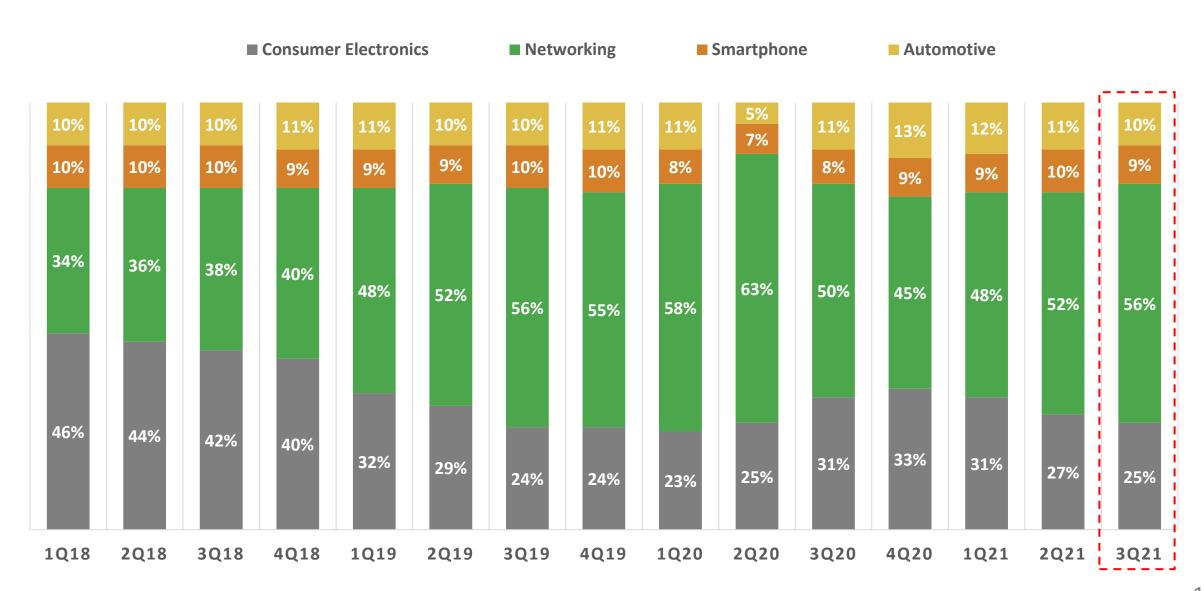




- The need for 5G commercialization and server upgrade to expedite the growth of high speed / frequency material demand
- ITEQ's market share in high speed / frequency material to uplift robustly

1Q18~3Q21 Product Mix

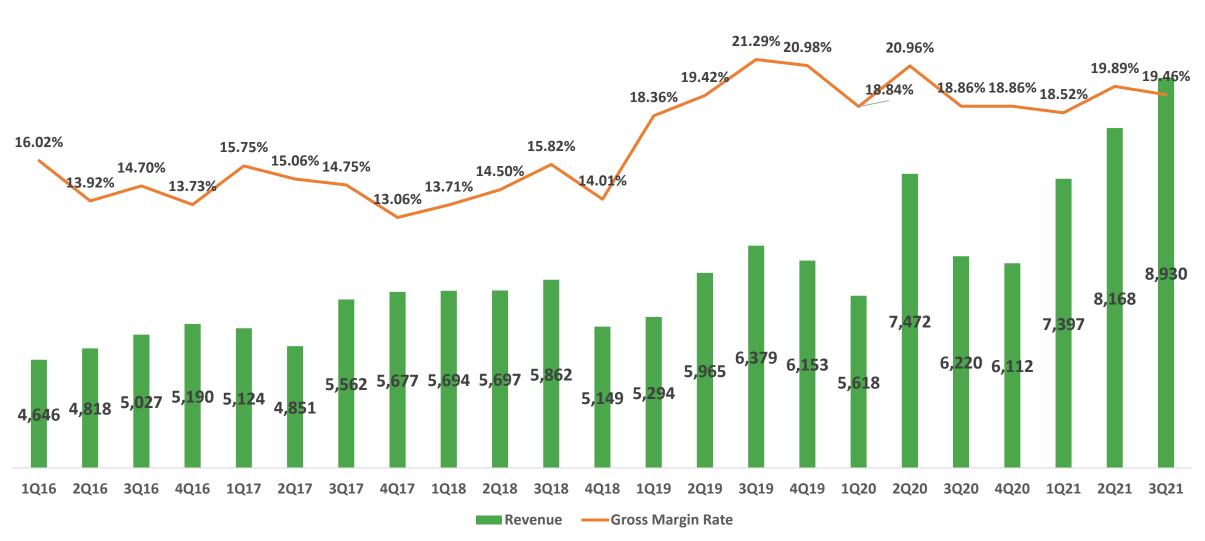




Revenue & Gross Margin Rate



(Million \$NTD)



3Q21 Income Statement



NTD \$Million	3Q21	2Q21	3Q20	QoQ	YoY
Revenue	8,930	8,168	6,220	9%	44%
Gross Profit	1,738	1,625	1,173	7%	48%
Operating Expense	631	483	454	31%	39%
Operating Profit	1,107	1,142	719	-3%	54%
Non-Op Income / Loss	(11)	(19)	97	-42%	-111%
Income before Tax	1,096	1,123	816	-2%	34%
Tax Expense	261	263	172	-1%	52%
Net Income to Parent	835	860	644	-3%	29%
EPS(NT\$)	2.40	2.58	1.94	-7%	24%
Key Financial Ratio					
Gross Margin	19.46%	19.89%	18.86%		
Operating Expense Ratio	7.07%	5.91%	7.30%		
Operating Margin	12.40%	13.98%	11.56%		
Effective Tax Rate	23.81%	23.42%	21.08%		
Net Margin	9.35%	10.53%	10.37%		

3Q21 Balance Sheet



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NTD \$Million	3Q21	2Q21	3Q20
Total Assets	36,035	32,698	25,953
Cash	4,035	2,749	3,625
Marketable Securities	5	5	6
NR / AR	14,100	13,403	11,200
Inventories	5,194	4,161	3,330
Fixed Assets	10,117	9,569	5,896
Total Liabilities	15,681	17,960	13,527
Short-term Debt	1,434	3,144	2,331
NP / AP	8,432	7,661	6,328
Long-term Debt		1,370	1,640
Total Equity	20,354	14,738	12,426
Key Financial Index			
Days Sales Outstanding	149	159	156
Days Sales of Inventory	66	64	56
Days Payable Outstanding	98	102	111
ROE (%)	18.50	20.80	23.90
ROA (%)	10.31	10.23	10.57
Debt ratio (%)	43.50	54.93	52.12
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Market Trend & Growth Drivers





Hunger for High Speed Transmission

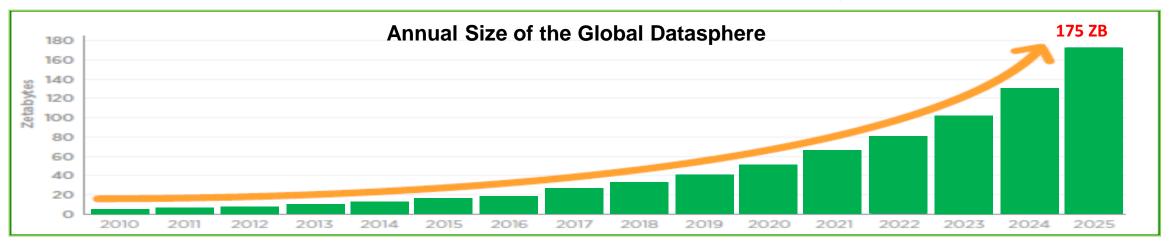


Rapid expansion of Global Datasphere

- Core (traditional and cloud datacenters)
- Edge (enterprise-hardened infrastructure such as, server rooms, servers in the field, cell towers, and smaller datacenters etc.)
- Endpoint (PCs, smartphones, and IoT devices)

Fast growing Global IP traffic

- UHD video streaming and internet gaming
- Connected home, work, health and car
- Big data and Al applications
- Cloud computing and cloud storage
- Virtual Reality (VR) and Augmented Reality (AR)



(Source: Data Age 2025, sponsored by Seagate with data from IDC Global DataSphere, May 2020)

 Rapid growth of global data traffic stimulates equipment upgrade to meet the need of low latency, high reliable and high speed computing

5G Network Infrastructure & Opportunities



Core (Telecom) + Transport Network:

- Including data center, Edge computing, OTN
- High efficient computing and massive data traffic

High Speed Material

Distributed + Centralized Unit (DU+CU)

- Including Macro Cell, Micro Cell to Small Cell
- Low latency and high speed requirements

High Speed Material

Active Antenna Unit (AAU)

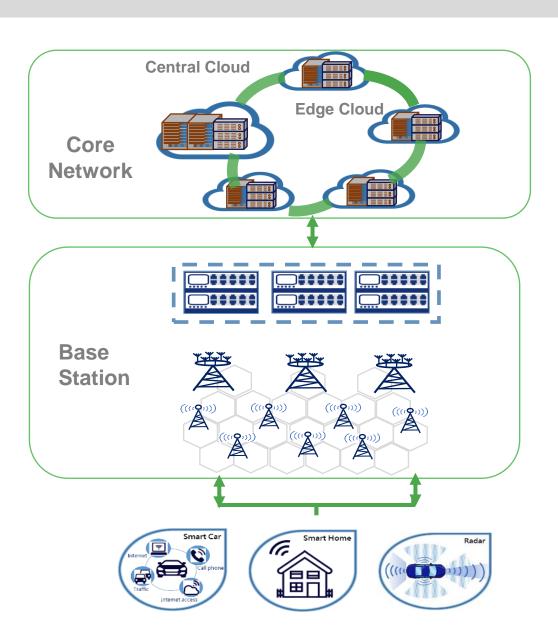
- Including Antenna, PA, TRX Network
- Multi layer design for complex functionality

High Speed Material

High Frequency Material

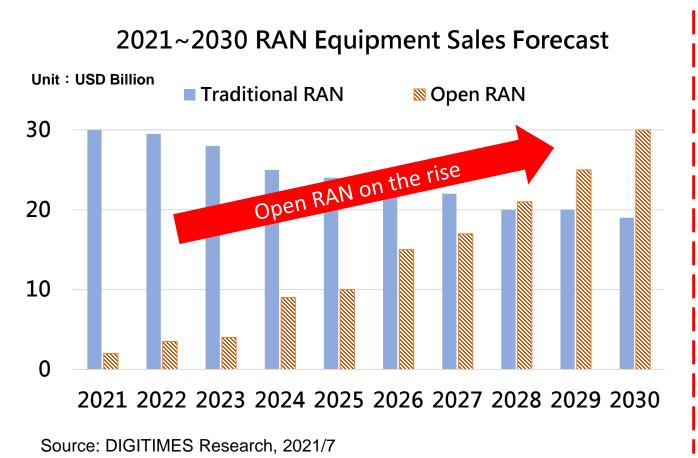
loT(Internet of Things)

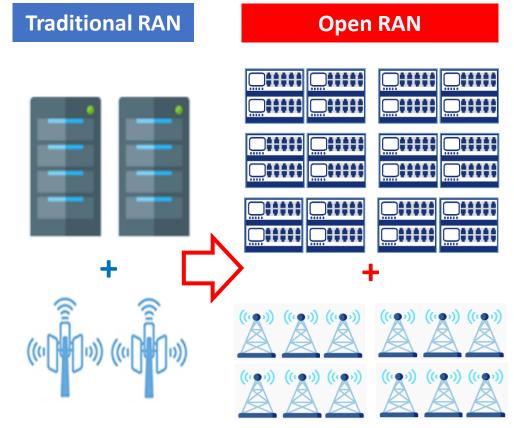
High Speed Material



Sustainable Growth Momentum (Telecom)





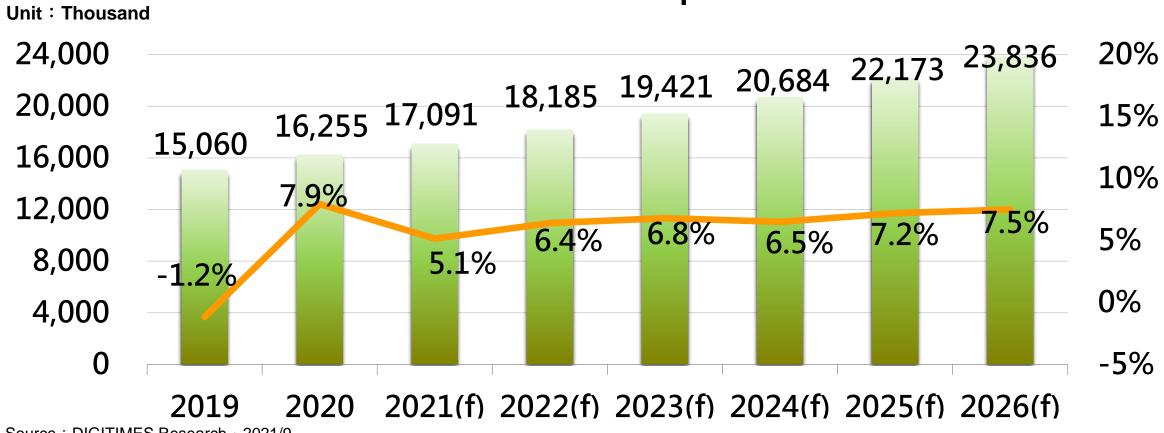


- Rising Open RAN Market: Another key driver to bring up the TAM for 5G network production value
- Potential opportunity for stronger CCL demand of edge computing servers and 5G Whitebox equipment

Sustainable Growth Momentum (Datacenter)







Source: DIGITIMES Research · 2021/9

Increase of Datacenter Equipment Shipment: Demand of high speed material to grow correlatively

Sustainable Growth Momentum (Datacenter)



	Platform	Purley		Whitley		Eagle Stream	
	CPU	Skylake	Cascade Lake	Copper Lake	Ice lake	Sapphire Rapids	Emerald Rapids
	Nano Process	14 nm	14 nm+	14 nm++	10 nm	Intel 7	Intel 7
Intel	PCIe Generation	PCle 3.0	PCle 3.0	PCle 3.0	PCIe 4.0	PCle 5.0	PCle 5.0
	MP Time	2017 Q3	2019 Q3	Cancel	2021 Q1	2022 Q2	2023 Q1
	CCL Material	Mid Loss	Mid Loss	Cancel	Low Loss	Very Low Loss	Very Low Loss
	Layer count	8 to 12	8 to 12	Cancel	12 to 16	16 to 20	16 to 20

	Architecture	Zen	Zen2	Zen3	Zen4
	CPU	Naples	Rome	Milan	Genoa
	Nano Process	14 nm (Global Foundries)	7 nm (TSMC)	7 nm (TSMC)	5 nm (TSMC)
AMD	PCle Generation	PCle 3.0	PCle 4.0	PCle 4.0	PCle 5.0
	MP Time	2017 Q3	2019 Q3	2020 Q4	2022 Q2
	CCL Material	Mid Loss	Low Loss	Low Loss	Very Low Loss
	Layer count	8 to 12	12 to 16	12 to 16	16 to 20



Datacenter Equipment Cyclical Upgrade to Drive the Following;

- Corresponding CCL material upgrade
- Increase consumption and layer counts for CCL

Manufacturing Site & Capacity – Expansion PlaniteQ



2014 – 2020 Dividend Policy



Year	EPS(NT\$)	Dividend(NT\$)	Cash Dividend(NT\$)	Pay-out Ratio(%)
2014	1.62	1.2	1.2	74%
2015	1.92	1.6	1.6	83%
2016	3.13	2.5	2.5	80%
2017	4.11	3.1	3.1	75%
2018	5.86	3.8	3.8	65%
2019	8.13	5.0	5.0	62%
2020	8.19	5.0	5.0	61%

^{*}New shares issuance of 30 million common shares concluded on March 31st 2020

^{**}New shares issuance of 50 million common shares concluded on September 2nd 2021; current total outstanding common share: 383 million

